

Edited by R. Hippler, H. Kersten,
M. Schmidt, K. H. Schoenbach

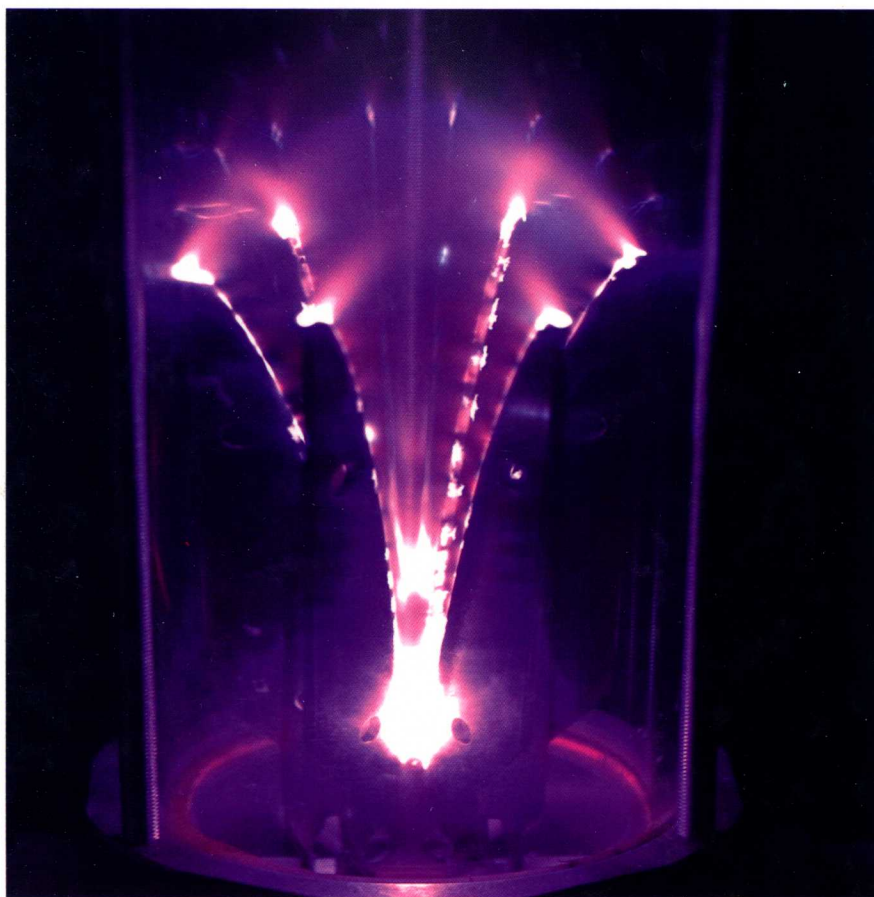
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Low Temperature Plasmas

Fundamentals, Technologies, and Techniques

Volume 2

Second, Revised and Enlarged Edition



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Fundamentals, Technologies and Techniques

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Edited by

*Rainer Hippler, Holger Kersten, Martin Schmidt,
and Karl H. Schoenbach*

2nd, Revised and Enlarged Edition



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The Editors

Rainer Hippler

University of Greifswald, Germany

Holger Kersten

University of Kiel, Germany

Martin Schmidt

Leibniz Institute for Plasma Science
and Technology e.V.,
Greifswald, Germany

Karl Schoenbach

Center for Bioelectrics,
Old Dominion University,
Norfolk, USA

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